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3A, 200V - 1000V Standard Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- High surge current capability
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber

MECHANICAL DATA

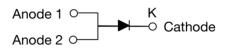
- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.107g (approximately)

KEY PARAMETERS			
VALUE	UNIT		
3	А		
200 - 1000	V		
100	А		
150 °C			
TO-277A (SMPC4.6U)			
Single die			
	VALUE 3 200 - 1000 100 150 TO-277A (SMP)		





TO-277A (SMPC4.6U)



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	TUAS 3DH	TUAS 3GH	TUAS 3JH	TUAS 3KH	TUAS 3MH	UNIT
Marking code on the dev	vice		AS3D	AS3G	AS3J	AS3K	AS3M	
Repetitive peak reverse	voltage	V _{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		١ _F	3					А
Surge peak forward current single half sine-					100			- A
wave superimposed on rated load	t = 1.0ms	I _{FSM}			260			A
Junction temperature T _J		T_{J}	-55 to +150				°C	
Storage temperature		T _{STG}	-55 to +150		°C			



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THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance	R _{ejl}	5.4	°C/W	
Junction-to-ambient thermal resistance	R _{eja}	46	°C/W	
Junction-to-case thermal resistance	R _{eJC}	8.9	°C/W	

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage ⁽¹⁾		$I_F = 1.5A, T_J = 25^{\circ}C$	V _F	0.88	-	V
		$I_F = 3.0A, T_J = 25^{\circ}C$		0.94	1.10	V
		$I_F = 1.5A, T_J = 125^{\circ}C$		0.76	-	V
		$I_F = 3.0A, T_J = 125^{\circ}C$		0.83	-	V
		T _J = 25°C	1	-	5	μA
Reverse current @ rated \	/ R`´	T _J = 125°C	I _R	11	-	μA
Junction capacitance	TUAS3DH TUAS3GH TUAS3JH	1MHz, V _R = 4.0V	CJ	27	-	pF
	TUAS3KH TUAS3MH			24	-	

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
TUAS3xH	TO-277A (SMPC4.6U)	6,000 / Tape & Reel	

Notes:

1. "x" define voltage from 200V(TUAS3DH) to 1000V(TUAS3MH)



TUAS3DH - TUAS3JH

100

1.6

CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

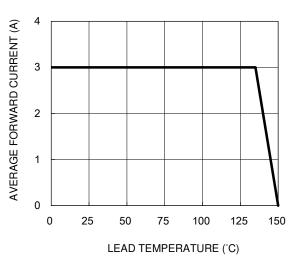
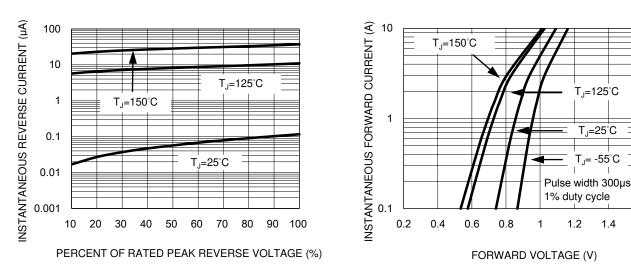


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics



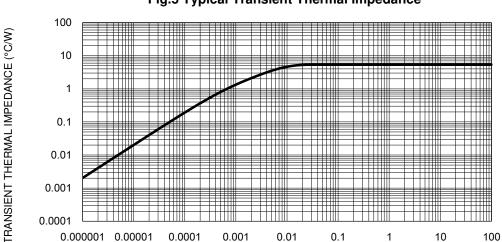


Fig.5 Typical Transient Thermal Impedance

PULSE DURATION (s)

Fig.2 Typical Junction Capacitance

TUAS3KH - TUAS3MH

10

Fig.4 Typical Forward Characteristics

REVERSE VOLTAGE (V)

100

CAPACITANCE (pF)

10

1

1

f=1.0MHz Vsig=50mVp-p

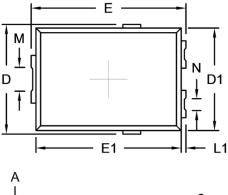
TUAS3DH – TUAS3MH

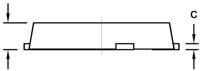
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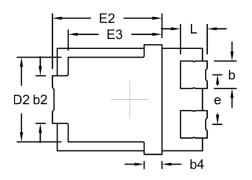


PACKAGE OUTLINE DIMENSIONS

TO-277A (SMPC4.6U)







SUGGESTED PAD LAYOUT

В

D

F

1

С

4

DIM.	Unit (mm)		Unit ((inch)
	Min.	Max.	Min.	Max.
A	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.75 (NOM.)	0.030	(NOM.)
с	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.94 (NOM.)	0.155	(NOM.)
е	2.08 (NOM.)	0.082	(NOM.)
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
М	0.65	1.15	0.026	0.045
N	0.25	0.75	0.010	0.030

Package body size D1 and E1 do not include mold flash Mold flash shall not exceed 0.1mm per side

Symbol	Unit (mm)	Unit (inch)
A	4.95	0.195
В	4.95	0.195
С	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

Notes:

A

1

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

MARKING DIAGRAM



Е

P/N YW F

= Marking Code

= Date Code

= Factory Code



TUAS3DH – TUAS3MH

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